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2SD1978

Silicon NPN Epitaxial, Darlington

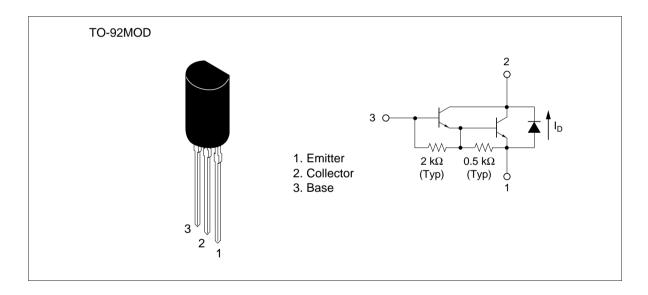


ADE-208-1162 (Z) 1st. Edition Mar. 2001

Application

- Low frequency power amplifier
- Complementary pair with 2SB1387

Outline



2SD1978

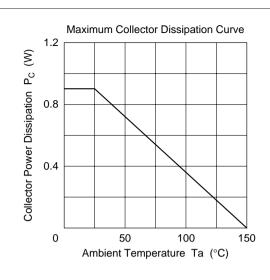
Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

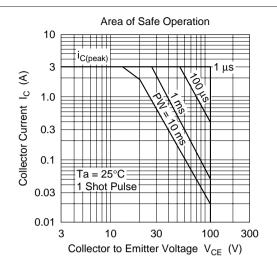
Item	Symbol		Unit	
Collector to base voltage	V_{CBO}	120	V	
Collector to emitter voltage	V_{CEO}	120	V	
Emitter to base voltage	V_{EBO}	7	V	
Collector current	I _c	1.5	А	
Collector peak current	ic (peak)	3.0	А	
Collector power dissipation	P _c	0.9	W	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	
E to C diode forward current	I _D	1.5	А	

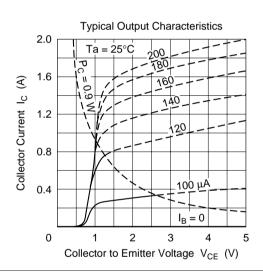
Electrical Characteristics ($Ta = 25^{\circ}C$)

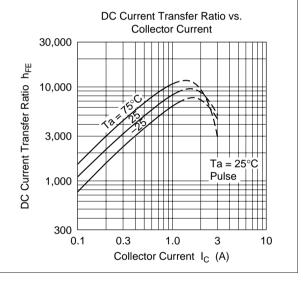
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	120	_	_	V	$I_{\rm C} = 0.1 \text{ mA}, I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	120	_	_	V	$I_{\rm C}$ = 10 mA, $R_{\rm BE}$ = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{E} = 50 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	1.0	μΑ	$V_{CB} = 100 \text{ V}, I_{E} = 0$
	I _{CEO}	_	_	10	μΑ	$V_{CE} = 100 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h_{FE}	2000	_	30000		$V_{CE} = 3 \text{ V}, I_{C} = 1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE}(\text{sat})1}$	_	_	1.5	V	$I_{C} = 1 \text{ A}, I_{B} = 1 \text{ mA*}^{1}$
	$V_{\text{CE(sat)2}}$	_	_	2.0	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)1}$	_	_	2.0	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA*}^{1}$
	V _{BE(sat)2}	_	_	2.5	V	$I_{\rm C}$ = 1.5 A, $I_{\rm B}$ = 1.5 mA* ¹
E to C diode forward voltage	V _D	_	_	3.0	V	I _D = 1.5 A*1

Note: 1. Pulse test

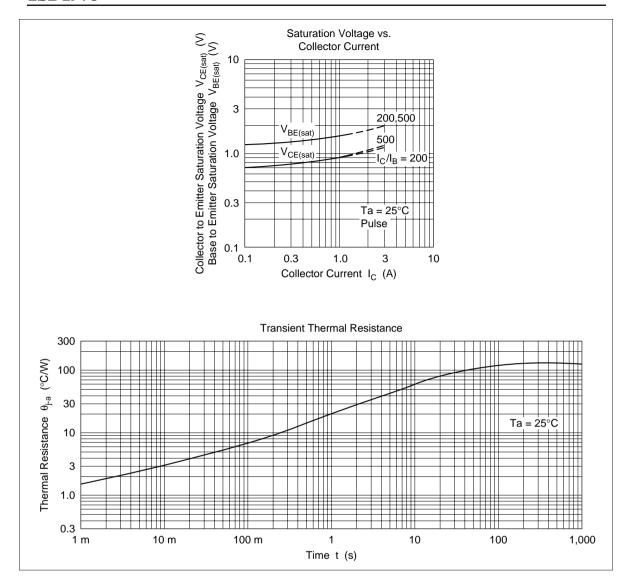




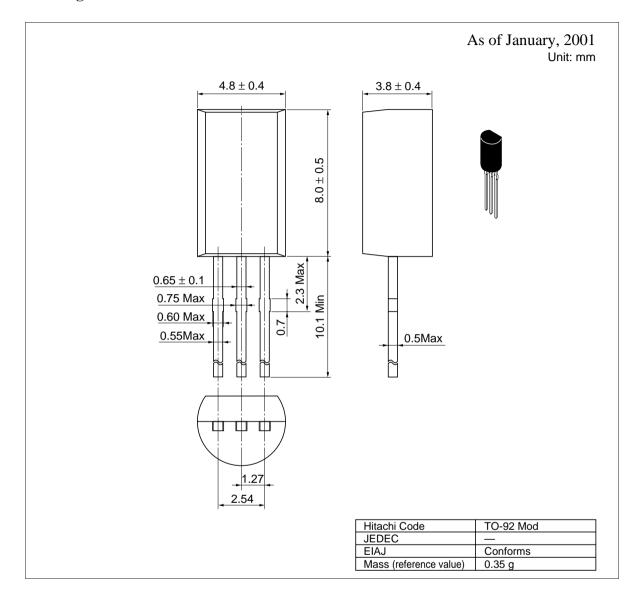




2SD1978



Package Dimensions



5

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